

Material Content Data Sheet

Sales Product Name	IM12B20EC1	**Issued**	25. March 2024
MA#	MA006034529		
Package	PG-MDIP-24-63	**Weight:**	6888.21 mg

Construction Element	Material group	Materials	CAS if applicable	Weight [mg]	Average mass [%]	Sum [%]	Average mass [ppm]	Sum [ppm]
chip_01	inorganic material	silicon	7440-21-3	6.694	0.10	0.10	972	972
chip_02	inorganic material	silicon	7440-21-3	3.285	0.05	0.05	477	477
chip_03	inorganic material	silicon	7440-21-3	3.285	0.05	0.05	477	477
chip_04	inorganic material	silicon	7440-21-3	3.285	0.05	0.05	477	477
chip_05	inorganic material	silicon	7440-21-3	3.285	0.05	0.05	477	477
chip_06	inorganic material	silicon	7440-21-3	3.285	0.05	0.05	477	477
chip_07	inorganic material	silicon	7440-21-3	3.285	0.05	0.05	477	477
chip_08	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	199	199
chip_09	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	199	199
chip_10	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	199	199
chip_11	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	199	199
chip_12	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	199	199
chip_13	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	199	199
leadframe	inorganic material	phosphorus	7723-14-0	0.390	0.01		57	
	non noble metal	iron	7439-89-6	1.300	0.02		189	
	non noble metal	copper	7440-50-8	1298.097	18.85	18.88	188452	188698
wire	noble metal	gold	7440-57-5	0.756	0.01		110	
	non noble metal	aluminium	7429-90-5	36.247	0.53	0.54	5262	5372
encapsulation	organic material	carbon black	1333-86-4	30.698	0.45		4457	
	plastics	epoxy resin	-	383.722	5.57		55707	
	inorganic material	silicondioxide	60676-86-0	3422.804	49.68	55.70	496907	557071
leadfinish	non noble metal	tin	7440-31-5	41.697	0.61	0.61	6053	6053
plating	non noble metal	nickel	7440-02-0	0.914	0.01	0.01	133	133
solder	non noble metal	antimony	7440-36-0	0.585	0.01		85	
	noble metal	silver	7440-22-4	1.463	0.02		212	
	non noble metal	tin	7440-31-5	3.803	0.06	0.09	552	849
glue	plastics	acrylic resin	-	0.249			36	
	plastics	maleimide resin	-	0.249			36	
	noble metal	silver	7440-22-4	0.746	0.01		108	
	inorganic material	silicondioxide	60676-86-0	0.778	0.01		113	
	plastics	epoxy resin	-	1.167	0.02	0.04	169	462
smd	inorganic material	silicondioxide	60676-86-0	0.003			1	
	noble metal	gold	7440-57-5	0.012			2	
	noble metal	palladium	7440-05-3	0.019			3	
	noble metal	silver	7440-22-4	0.030			4	
	organic material	ethyl cellulose	9004-57-3	0.024			4	
	organic material	DEGBE	112-34-5	0.105			15	
	inorganic material	cobalt(II)oxide	1307-96-6	0.200			29	
	inorganic material	copperoxide	1317-38-0	0.576	0.01		84	
	inorganic material	manganesedioxide	1313-13-9	0.658	0.01	0.02	96	238
pcb metal	non noble metal	copper	7440-50-8	21.446	0.31	0.31	3113	3113
pcb plastic	plastics	epoxy resin	-	105.646	1.53		15337	
	inorganic material	glass fibre wool	65997-17-3	129.123	1.87	3.40	18745	34082
pcb plating	noble metal	gold	7440-57-5	0.066			10	
	non noble metal	nickel	7440-02-0	3.029	0.04	0.04	440	450
dcb ceramic	inorganic material	zirconium dioxide	1314-23-4	7.862	0.11		1141	
	inorganic material	aluminum nitride	24304-00-5	697.271	10.12	10.23	101227	102368

dcb metal	non noble metal	copper	7440-50-8	661.840	9.61	9.61	96083	96083
deviation	< 10%				Sum in total:	100.00		1000000

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